

LIST OF CURRENT CLAIMS

1-17. (Canceled)

18. (Currently Amended) A method for incorporating a chip into a smart card, said chip having ~~front and back sides~~ an active front and a back side, and being thinned from the back side, the method comprising the steps of applying the thinned chip to a surface of the smart card with the chip front side directed outwardly from the smart card surface such that the smart card surface forms an external surface of a finalized smart card, and then providing the card and chip with conductive paths.

19. (Canceled)

20. (Previously Presented) The method according to claim 18, including incorporating the chip into a cavity in the surface of the smart card.

21. (Previously Presented) The method according to claim 18, including pressing the chip into the surface of the smart card flush under the action of heat.

22. (Previously Presented) The method according to claim 18, including coating the chip located on the surface of the smart card with a protective lacquer.

23-26. (Canceled)

27. (Currently Amended) A smart card comprising a smart card body having at least one chip, said chip having ~~front and back sides~~ an active front and a back side, and being thinned from the back side, the chip being disposed on a surface of the smart card body with the chip front side directed outwardly from the smart card surface, said smart

card body surface forming an external surface of the smart card wherein printed conductive paths are applied to the smart card and the chip on the outside thereof.

28. (Canceled)

29. (Canceled)

30. (Previously Presented) The smart card according to claim 27, wherein the chip is disposed in a cavity in the surface of the smart card.

31. (Previously Presented) The smart card according to claim 27, wherein the chip is pressed into the surface of the smart card flush.

32. (Previously Presented) The smart card according to claim 27, wherein the chip is coated with a protective lacquer.

33. (Currently Amended) A method for incorporating a chip into a smart card having a finalized plastic card body, said chip having ~~front and back sides~~ an active front and a back side, and being thinned from the back side, the method comprising the steps of:

applying the chip to a card body surface with the chip front side facing outwardly from the card body surface, said card body surface forming an external surface of the smart card; and

providing the card body and chip with conductive paths;

wherein the chip is permanently secured by the card body.

34. (Canceled)

35. (Previously Presented) The method according to claim 33, further comprising the step of incorporating the chip into a cavity in the surface of the card body.

36. (Previously Presented) The method according to claim 33, further comprising the step of pressing the chip into the surface of the card body flush under the action of heat wherein the material of the card body surrounds the entirety of the chip with the exception of a front side of the chip facing outwardly from the surface of the card body.

37. (Previously Presented) The method according to claim 33, further comprising the step of coating the chip located on the surface of the card body with a

38. (Previously Presented) The method according to claim 33, wherein the card body consists a single card body.

39. (Currently Amended) A smart card comprising a plastic card body having at least one chip disposed on a card body surface, said chip having ~~front side and back sides~~ an active front and a back side, and being thinned from the back side, wherein the chip is permanently secured by the card body with the chip front side directed outwardly from the card body surface; wherein said card body surface forms an external surface of the smart card; wherein printed conductive paths are applied to the card body and the chip on the outside thereof.

40. (Canceled)

41. (Canceled)

42. (Previously Presented) The smart card according to claim 39, wherein the chip is disposed in a cavity in the surface of the card body.

43. (Previously Presented) The smart card according to claim 39, wherein the chip is pressed into the surface of the card body flush.

44. (Previously Presented) The smart card according to claim 39, wherein the chip is coated with a protective lacquer.

45. (Previously Presented) The smart card according to claim 39, wherein the card body consists a single card body.

46. (Cancelled)

47. (Cancelled)

48. (Cancelled)

49. (Previously Presented) The method of claim 18, wherein the step of providing the conductive paths includes printing the conductive paths.

50. (Previously Presented) The method according to claim 18, wherein the step of applying the thinned chip to the surface of the smart card includes applying the thinned chip on an outermost surface of the smart card.

51. (Previously Presented) The smart card according to claim 27, wherein the thinned chip is applied on an outermost surface of the smart card.